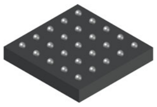
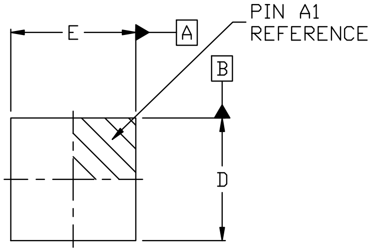
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



WLCSP25 1.88x1.84x0.30, 0.35P
CASE 567LA
ISSUE B

DATE 09 AUG 2023

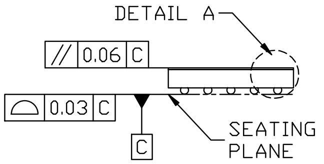


TOP VIEW

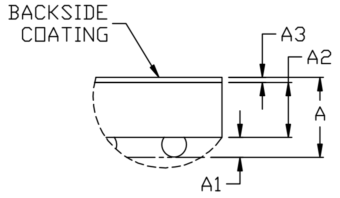
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

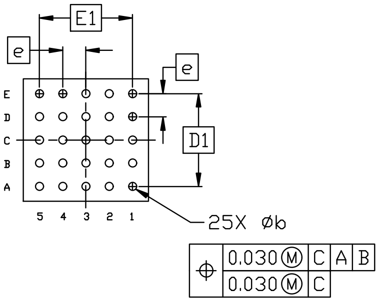
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.360	0.400	0.440
A1	0.070	0.100	0.130
A2	0.262	0.275	0.288
A3	0.025 BSC		
b	0.095	0.125	0.155
D	1.818	1.848	1.878
D1	1.400 BSC		
E	1.854	1.884	1.914
E1	1.400 BSC		
e	0.350 BSC		



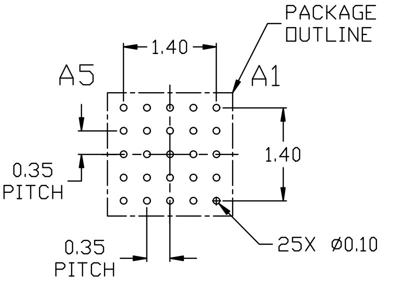
SIDE VIEW



DETAIL A
SCALE 3:1



BOTTOM VIEW



RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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